

Fair-Rite P/N **274455577**

44 Material Grade

Nominal Chemical Composition

<u>Compound</u>	<u>CAS Number</u>	<u>wt %</u>	Wt of core (g)= 0.851	
Fe2O3	1309-37-1	63.97	0.5444	Compound Weight (g) Breakdown of 44 Material
ZnO	1314-13-2	21.00	0.1787	
NiO	1313-99-1	11.00	0.0936	
CuO	1317-38-0	4.00	0.0340	
Bi2O3	1304-76-3	0.03	0.0003	

Pb-Free Plated Round Cu Wire

<u>Element</u>	<u>CAS Number</u>	<u>wt%</u>	Wt of wire (g)= 0.109	
Cu	7440-50-8	94.4	0.10290	Element Weight (g) Breakdown of Pb- Free Plated Round Cu Wire
Plating:				
Ni	7440-02-0	0.9	0.00098	
Sn	7440-31-5	4.7	0.00512	

Calculated Maximum Levels of RoHS3 (EU Directive 2015/863) Restricted Substances Present in 44 Material Grade

<u>Impurity Substance</u>	<u>RoHS Threshold (ppm)</u>	<u>ppm</u>	Wt of core (g)= 0.851	
Cr+6	1000	0.00	0	RoHS Impurity Substance Weight (g) Breakdown of 44 Material
Cd	100	6.09	5.18259E-06	
Hg	1000	0.09	7.659E-08	
Pb	1000	10.90	9.2759E-06	
PBB	1000	0.00	0	
PBDE	1000	0.00	0	
Bis(2-Ethylhexyl) phthalate (DEHP)	1000	0.00	0	
Benzyl butyl phthalate (BBP)	1000	0.00	0	
Dibutyl phthalate (DBP)	1000	0.00	0	
Diisobutyl phthalate (DIBP)	1000	0.00	0	

Supporting notes:

- P/N 274455577 consists of:
 - core 44 Material Grade
 - wire Pb-Free Plated Round Cu Wire
- Moisture Sensitivity Level (MSL)= 1
- Max Reflow Temp= 260 degC
- Max Time at Max Reflow Temp= 40 sec
- RoHS 6/6 Compliant Terminations/ Wire are backwards compatible with standard Soldering Processes
- RoHS Conversion Date= 1/1/2005
- RoHS Compliance Marking is Contained on Shipping Labels